

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MARIA CLEMENS YPIL QUINONES	02/22/2019
ELSIE AGDON CABAUG	02/22/2019
JEROME TEYSSEYRE	02/26/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
<b>Street Address:</b>	5005 E. MCDOWELL ROAD
<b>Internal Address:</b>	MAILDROP A700
<b>City:</b>	PHOENIX
<b>State/Country:</b>	ARIZONA
<b>Postal Code:</b>	85008
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16506405
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(602)244-3169
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<b>Phone:</b>	6022443574
<b>Email:</b>	patents@onsemi.com
<b>Correspondent Name:</b>	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
<b>Address Line 1:</b>	5005 E. MCDOWELL ROAD
<b>Address Line 2:</b>	MAILDROP A700
<b>Address Line 4:</b>	PHOENIX, ARIZONA 85008
<b>ATTORNEY DOCKET NUMBER:</b>	ONS03184US
<b>NAME OF SUBMITTER:</b>	SHARRON CASTILLO
<b>SIGNATURE:</b>	/Sharron Castillo/
<b>DATE SIGNED:</b>	07/09/2019
<b>Total Attachments: 4</b>	
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For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name	of (City and State OR Country)
MARIA CLEMENS YPIL QUINONES	CEBU CITY PHILIPPINES
ELSIE AGDON CABAUG	CONSOLACION PHILIPPINES
JEROME TEYSSEYRE	SCOTTSDALE, ARIZONA US

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

**Title: SEMICONDUCTOR PACKAGE WITH HEATSINK**

**Attorney Docket No.: ONS03184US**

**Serial No.:** 16/506405

**Filing Date:** July 9, 2019

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

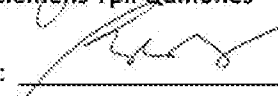
We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

We hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

By (Inventor signature):   
Maria Clemens Ypil Quinones

Witnessed by (Witness signature): 

Printed name of Witness: Romel Manatao

Signed and Witnessed on this 22 day of Feb, 2019  
day month year

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By (Inventor signature):   
Elsie Agdon Cabahug

Witnessed by (Witness signature): 

Printed name of Witness: Romel Manatao

Signed and Witnessed on this 22 day of FEB, 2019  
day month year

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name	of (City and State OR Country)
MARIA CLEMENS YPIL QUINONES	CEBU CITY PHILIPPINES
ELSIE AGDON CABAUG	CONSOLACION PHILIPPINES
JEROME TEYSSEYRE	SCOTTSDALE, ARIZONA US

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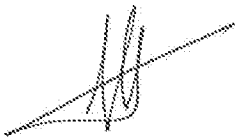
together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

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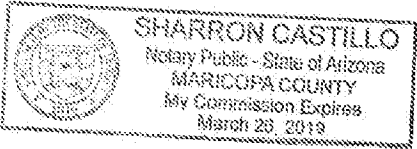
Jerome Teysseyre

ACKNOWLEDGMENT

State of Arizona        )  
  )  
County of Maricopa    )

On this 26<sup>th</sup> day of February, 2019, before me personally appeared, **Jerome Teysseyre**, whose identity was proven to me on the basis of satisfactory evidence to be the person who he/she claims to be, and acknowledged that he/she signed the above/attached document.

(seal)



  
Notary Public